# Sensors, Signals and Noise

### COURSE OUTLINE

- Introduction
- Signals and Noise
- Filtering
- Sensors and electronics: PhotoDetectors PD1



## TBD - Photon features and data

- Photon in the visible spectral range: features and data
- Photon statistics and noise
- Photon absorption in materials: absorption coefficient and penetration length
- Photon-Energy detectors: basic principle and main features
- Photon-Quanta detectors : basic principle and main features



## TBD – Photon-Energy Detectors

- Detector components and structure
- Steady state response
- Heating transients and dynamic response
- Radiant Sensitivity or Spectral Responsivity
- Bolometers and Thermopiles
- Outline of imaging detectors: focal plane arrays



## TBD – Photon-Quanta Detectors

- External photoelectric effect: Photo-emission of electrons from material in vacuum
- Internal photoelectric effect: photo-generation of free carriers in semiconductors
- Physics of the photoelectric effect: outline, main features, inherent limitations
- Photon detection efficiency (Quantum detection efficiency)
- Relation between Quantum detection efficiency and Spectral Responsivity



### Photocathode: photoelectron emission in vacuum





### Photocathode: photoelectron emission in vacuum



It's a 3-step process:

- 1. free electron generation
- 2. electron propagation through cathode
- 3. escape of electron into the vacuum



### Semi-transparent photocathode







### Semi-transparent photocathode





### Photocathode: photoelectron emission in vacuum





### Radiant Sensitivity or Spectral Responsivity



make possible to read directly from the diagram also the QDE



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### **Quantum Detection Efficiency**







#### Absorption Coefficient of Silicon











rv 2013/05/30





Simple planar device structure





Epitaxial planar device structure



- Deep diffused guard ring
- $V_{BD}$  control by p+ implantation
- fully isolated structure
- Short diffusion tail



#### p-p<sup>+</sup>-n Double-Epitaxial device



- No guard-ring
- Active area defined by p+ implantation
- Adjustable V<sub>BD</sub> and E-field
- suitable for integration and array detector
- Short diffusion tail (simple exponential)



### Device in standard CMOS technology





Etched device structure for deep depletion layer (reach-through photodiode)





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Improved reach-through device structure





### Dark Current comparison: photocathode vs silicon PD

#### Data @ Room Temperature

**Photocathode** with diameter 1" (2,54 cm), current good devices:

- Primary Dark Current I<sub>D</sub> < 1000 electrons / s
- i.e., current density  $j_D < 200$  electrons / cm<sup>2</sup> s

= 2 x 10  $^{-6}$  elet / ( $\mu$ m)<sup>2</sup> s

Silicon Photodiode with active area diameter 200  $\mu$ m, best available devices:

- Primary Dark Current I<sub>D</sub> < 1000 electron / s
- i.e., current density  $j_D < 4 \times 10^{+6}$  elet / cm<sup>2</sup> s =

= 4 x 10 <sup>- 2</sup> el (µm)<sup>-2</sup> s

The Si-photodiode DC density  $j_{D}$  is higher by a factor > 20.000



## Dark Current of Si junction reverse biased

In reverse-biased Silicon junctions thermal generation rate of carriers occurs over all the depleted volume with volume density  $n_G$ 

$$n_G = \frac{n_i}{2\tau}$$

- $n_i$  intrinsic carrier density @ Room Temperature is  $n_i = 1,45 \ge 10^{10} \text{ cm}^{-3}$
- *τ* minority carrier lifetime
   is strongly dependent on the technology,
   i.e on the fabrication process and on the starting material.
- Typical values
  - $\tau \sim \mu s$  ordinary integrated circuits
  - $\tau \sim ms$  high quality technology for detector devices
  - $\tau \sim s$  best available etechnology for detector devices



### Dark Current of Si junction reverse biased

In a photodiode with round active area A (diameter D) and depletion layer thickness w the total generation rate is

$$n_{\rm D} = n_G A W$$

In order to limit it  $n_D < n_{Dmax}$  we must limit the area A=  $\pi D^2/4$ 

$$A < A_{max} = n_{Dmax} / n_G w$$

The corresponding limit for D can be expressed as a function of the thickness and of the miniority carrier lifetime (i.e of the actual device technology)

$$D \le D_{\max} = \sqrt{8n_{D\max}\tau/\pi n_i w}$$

Example: with w = 1 $\mu$ m, for keeping  $n_{Dmax}$  = 10 <sup>3</sup> el / s at room temperature

D < D<sub>max</sub> = 420  $\tau^{1/2}$  (D in µm if  $\tau$  is in seconds)

With good technology
$$\tau \sim 10 \text{ms} \rightarrow D_{\text{max}} = 42 \,\mu\text{m}$$
With excellent technology $\tau \sim 1\text{s} \rightarrow D_{\text{max}} = 420 \,\mu\text{m}$ With exceptional technology $\tau \sim 10\text{s} \rightarrow D_{\text{max}} = 1.33 \,\text{mm}$ 



Circuit Noise impairs sensitivity of Analog Detectors





Single-Photon Detectors bypass the Electronic Noise Limit





## PhotoMultiplier Tube PMT





### Semi-transparent photocathode





## **Optical Absorption of Semiconductors**





### Photon absorption and carrier collection



## Photon Detection Efficiency: long $\lambda$ detectors





## Silicon Ionization Coefficients



